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Application Number

08/949 850

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United States Patent Application Publication No. _____, page, _____ line _____,

United States Patent Number 6559 379, column _____, line, _____.

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(12) **United States Patent**
Solanki et al.

(10) **Patent No.:** **US 6,559,379 B2**
(45) **Date of Patent:** **May 6, 2003**

- (54) **PRESSURE SENSOR WITH TRANSDUCER MOUNTED ON A METAL BASE**
- (75) Inventors: **Dinesh Solanki**, Santa Clara, CA (US);
Janusz Bryzek, Fremont, CA (US)
- (73) Assignee: **NovaSensor, Inc.**, Fremont, CA (US)
- (*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.
- (21) Appl. No.: **09/815,900**
- (22) Filed: **Mar. 22, 2001**
- (65) **Prior Publication Data**
US 2001/0009195 A1 Jul. 26, 2001

Related U.S. Application Data

- (63) Continuation of application No. 08/949,850, filed on Oct. 14, 1997, now abandoned, which is a continuation of application No. 08/393,956, filed on Feb. 24, 1995, now abandoned.

- (51) Int. Cl.⁷ **H05K 5/06**
- (52) U.S. Cl. **174/52.2; 174/52.4; 257/676**
- (58) Field of Search **174/52.2, 52.4; 257/676, 675, 712, 713; 73/727, 756**

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(57) ABSTRACT

A three piece housing, designed to house semiconductor chips is molded using a polymer material. The chip sits on a metal base. Electrical leads pass through a molded housing to provide electrical contact between the semiconductor chip and external circuitry.

31 Claims, 5 Drawing Sheets

